

Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms to requirements laid down in Annex II of the Commission Regulation 2019/424.

- 3(1)(a): See Section 1.1 of the system manual for the product type.
- 3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.
- 3(1)(c): See the title page of the system manual for product model number(s).
- 3(1)(d): See the serial number on the physical system to determine the year of manufacture.
- 3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

PSU Model PWS-2K09F-1R Watts: 2000W	PSU Efficiency				Power Factor
	10 %	20 %	50 %	100 %	50 %
Single Output (AC-DC)	92.80%	94.89%	96.09%	94.53%	0.99
Multiple Output (AC-DC)	N/A	N/A	N/A	N/A	N/A

System (EUT) Efficiency in **Idle State** Power (Table)

Representative Configurations	Measured Idle State Power (W)	Calculated Idle Power Allowance (W)
High-End Performance Configuration	714	1249.546
Typical Configuration	N/A	N/A
Low-End Performance Configuration	205.3	512.0145

System (EUT) Efficiency in **Active State** Power (Table)

Representative Configurations	Active State Efficiency Score (Effserver)	Minimum Active State Efficiency for 2-Socket Server
High-End Performance Configuration	46.6	9.5
Typical Configuration	N/A	
Low-End Performance Configuration	52.9	

3(1)(k): The operating condition class is **A2**.

Operating condition class	Dry bulb temp °C		Humidity range, non-condensing		Max dew point (°C)	Maximum rate of change (°C/hr)
	Allowable range	Recommended range	Allowable range	Recommended range		
A1	15- 32	18-27	- 12 °C Dew Point (DP) and 8 % relative humidity (RH) to 17 °C DP and 80 % RH	- 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	- 12 °C DP and 8 % RH to 21 °C DP and 80 % RH	Same as A1	21	5/20
A3	5-40	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 85 % RH	Same as A1	24	5/20
A4	5-45	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 90 % RH	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 842.52 W.

3(1)(m): The active state efficiency and performance is 46.6.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X10/X11/H11/H12/M11 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:
https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_Utility/

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family : SYS-221GE-NR

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

Illustrated System Disassembly Instructions

Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.

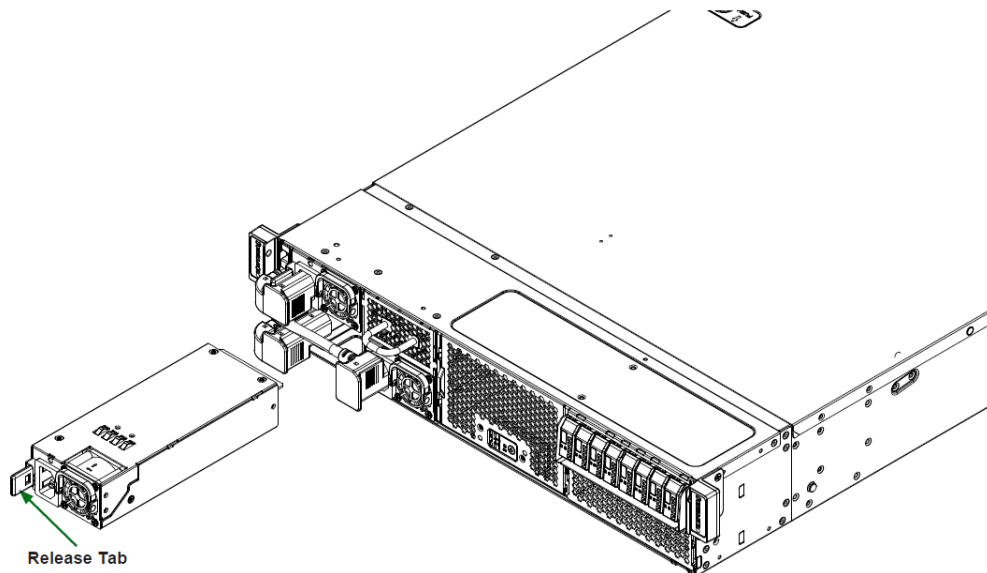
CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!

1. Power Supply Module

Type and number of fastenings: One (1) latch per module.

Tools required: None.

Procedure: Unplug the power cord from the power supply. Push the release tab on the front of the power supply module and pull the module using the handle.



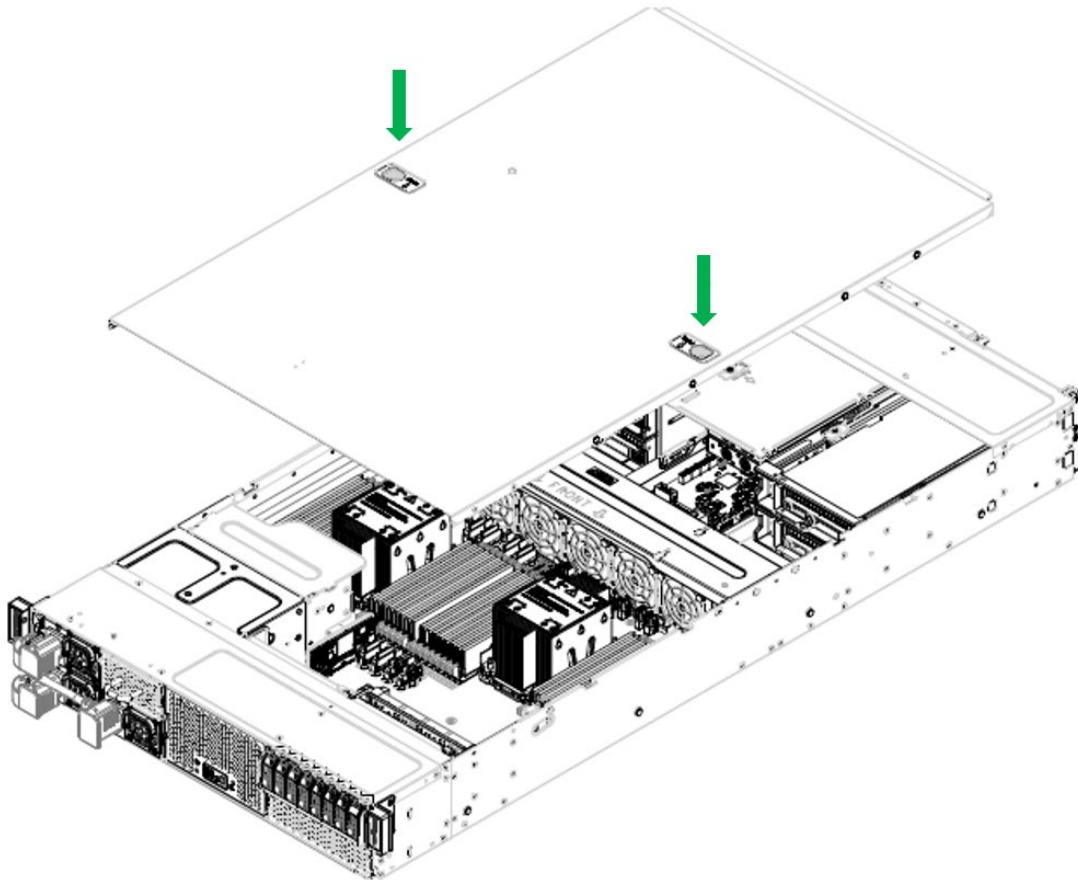
2. Chassis Cover

Type and number of fastenings: Three (3) screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the screws on the side of the cover.
2. Press the release buttons. Slide the cover toward the front and lift away from the chassis.

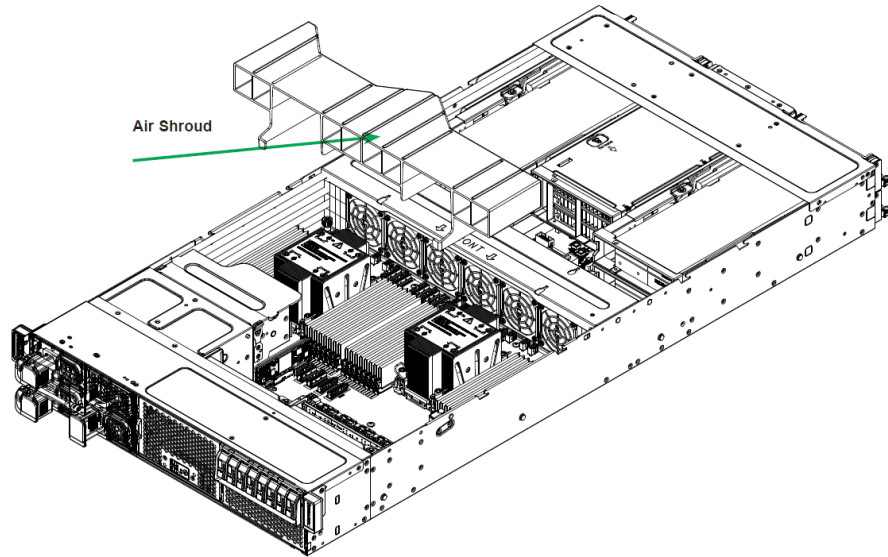


3. Air Shroud

Type and number of fastenings: None

Tools required: None.

Procedure: Lift the plastic air shroud up and away from the motherboard.

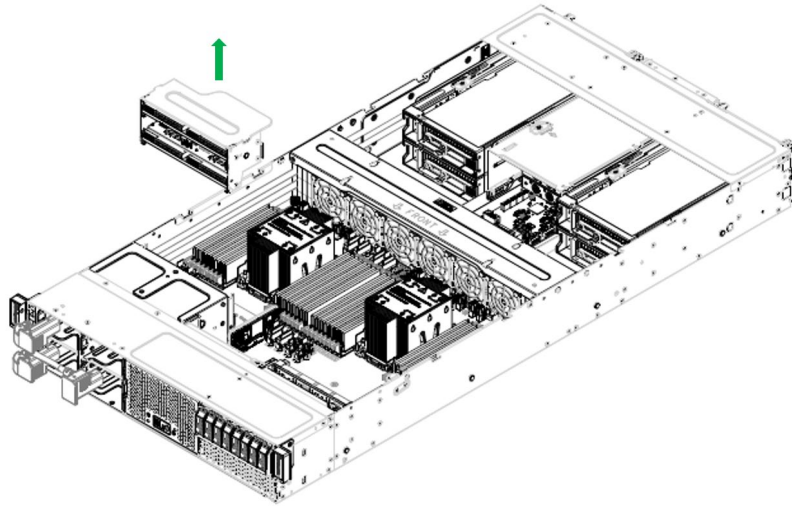


4. Power Distribution Board Module

Type and number of fastenings: None.

Tools required: None.

Procedure: After the three power supply modules have been unplugged from the chassis, lift the power distribution board module up and away from the chassis.

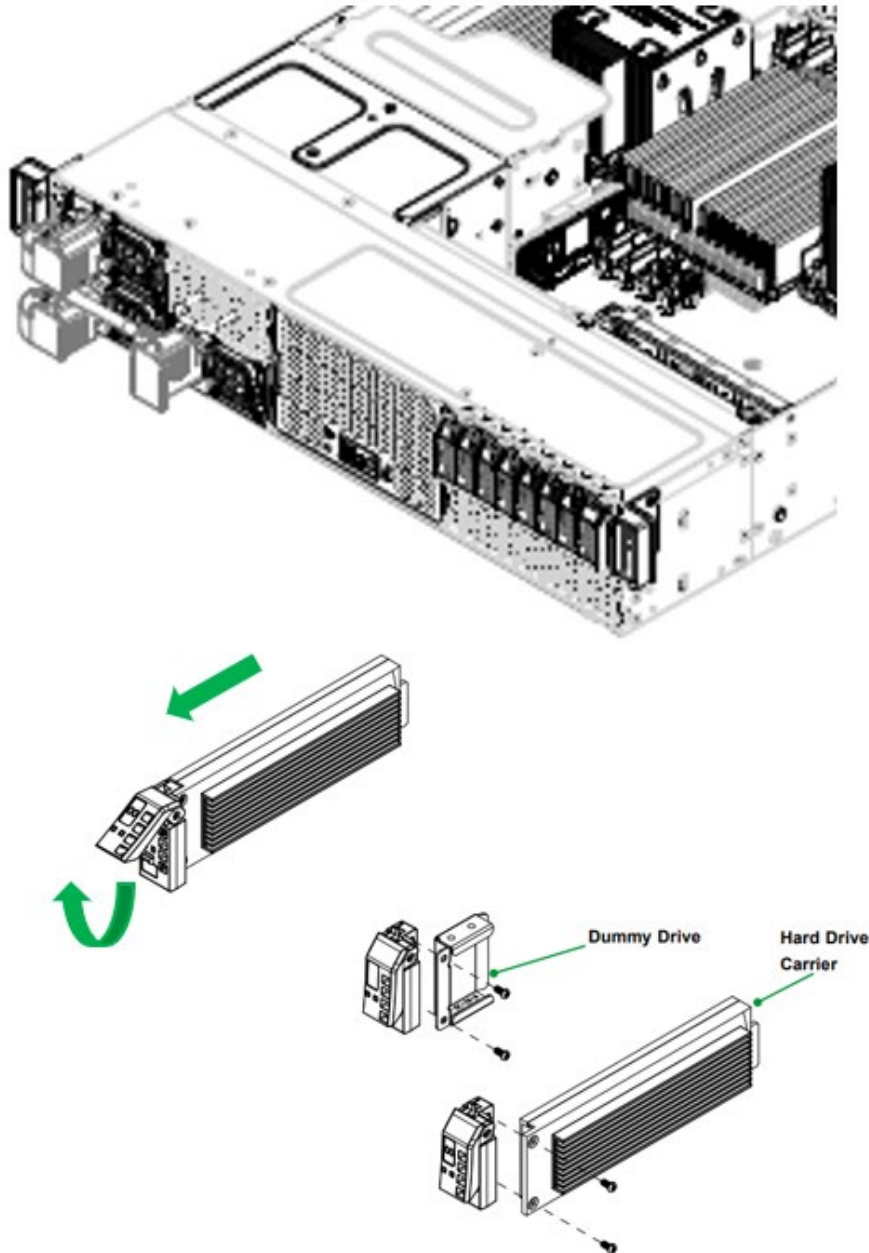


5. Data Storage Devices (E1.S)

Type and number of fastenings: One (1) locking lever per drive or dummy drive.

Tools required: None.

Procedure: Lift the locking lever and pull the drive or dummy drive out of the chassis.

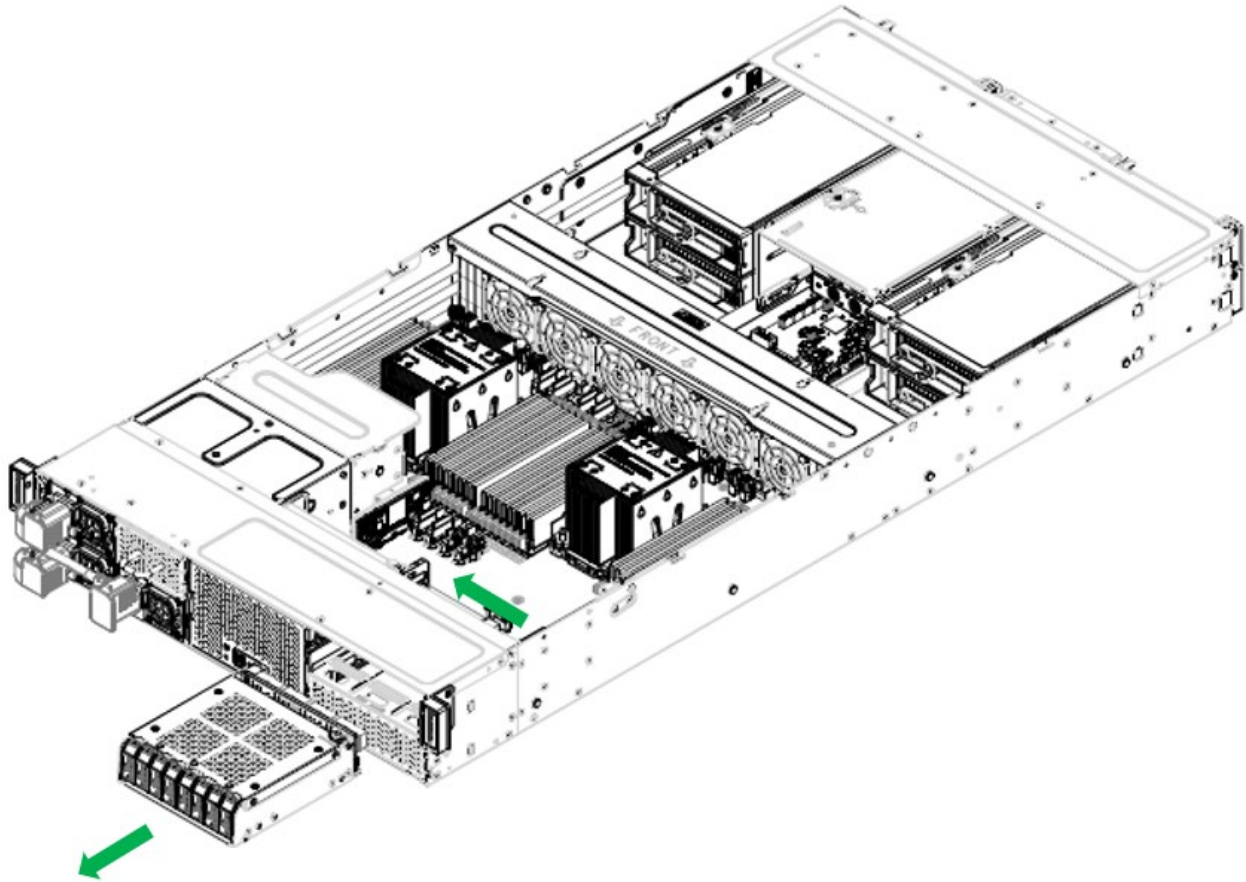


6. Data Storage Devices (E1.S) Drive Bay

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Slide the release button and pull the drive bay away from the chassis.

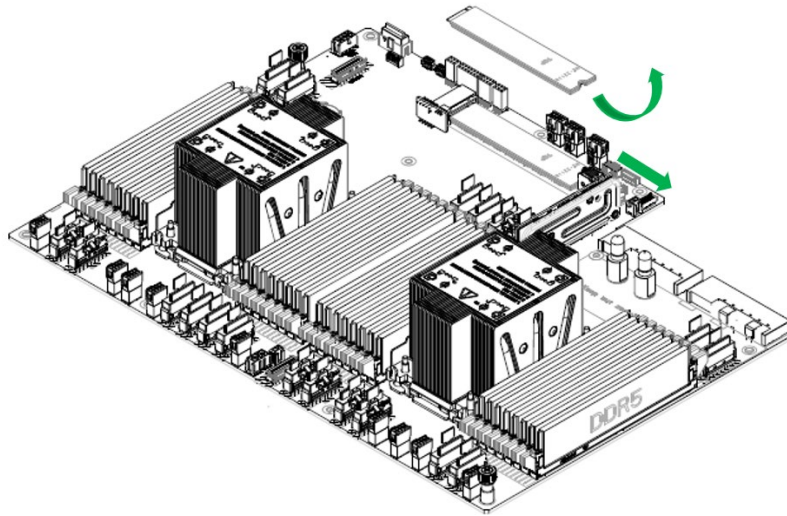


7. Data Storage Devices (M.2)

Type and number of fastenings: One (1) 2-in-1 locking clip.

Tools required: None.

Procedure: Pull the locking clip and unplug the drives. Pull the drives up and away from the motherboard.

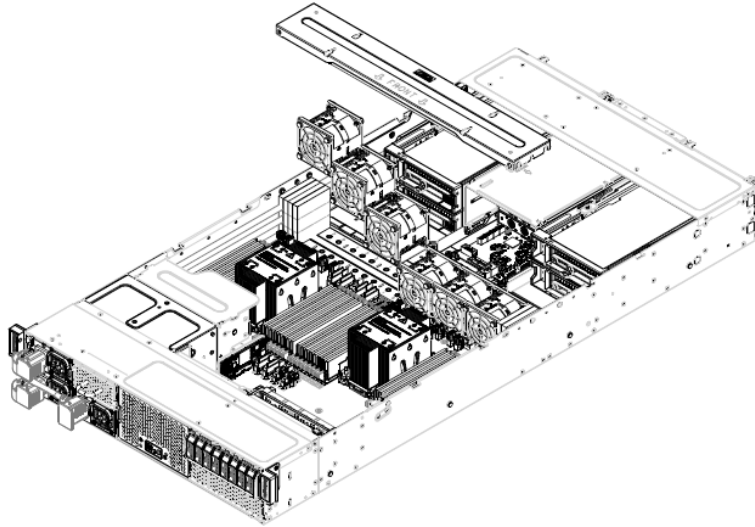


8. Fans

Type and number of fastenings: None.

Tools required: None.

Procedure: Lift the fan bracket from the top of the fans. Lift the fans from the chassis.

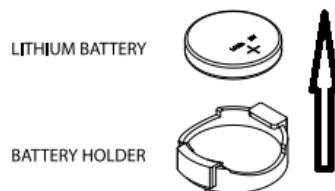


9. Batteries

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.

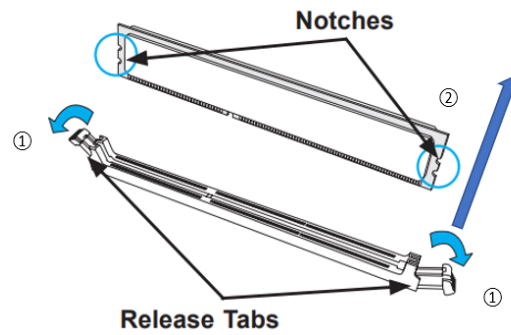


10. Memory

Type and number of fastenings: Two (2) release tabs per memory module.

Tools required: None.

Procedure: Press both release tabs on the ends of the memory module to unlock it. Once the module is loosened, remove it from the memory slot.



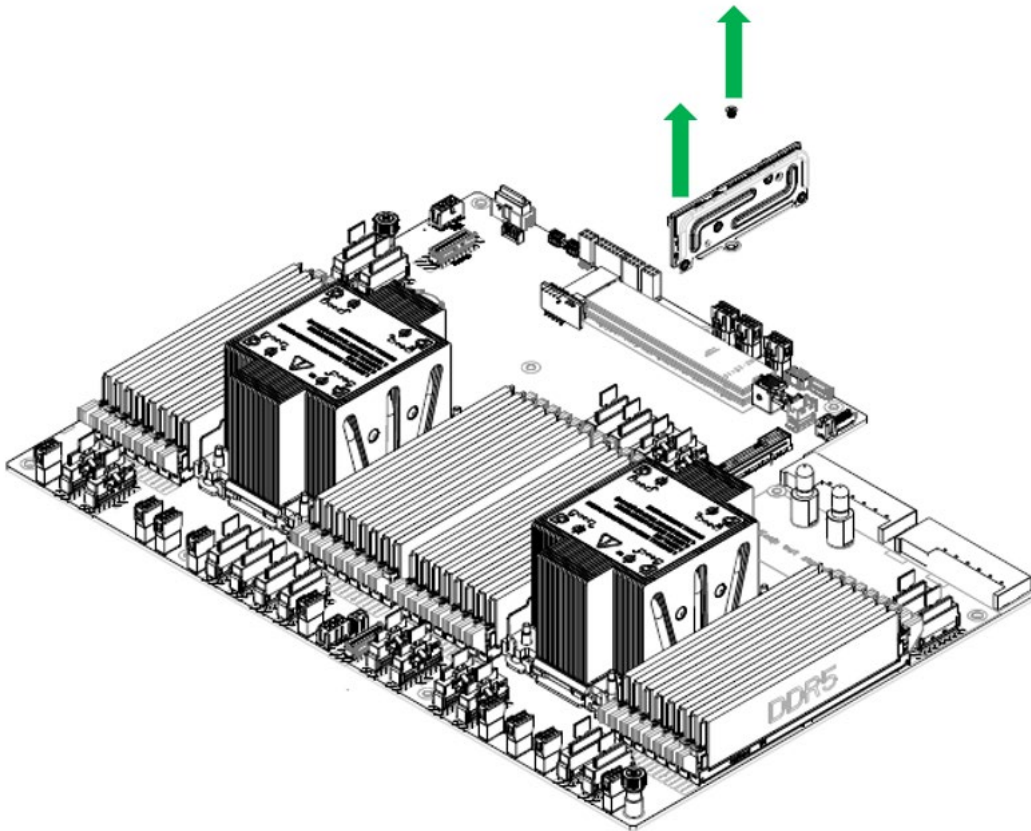
11. BMC Module

Type and number of fastenings: One (1) screw

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the cable connecting the BMC module from the motherboard.
2. Unscrew the BMC module metal plate from the motherboard.
3. Lift the BMC module away from the motherboard.



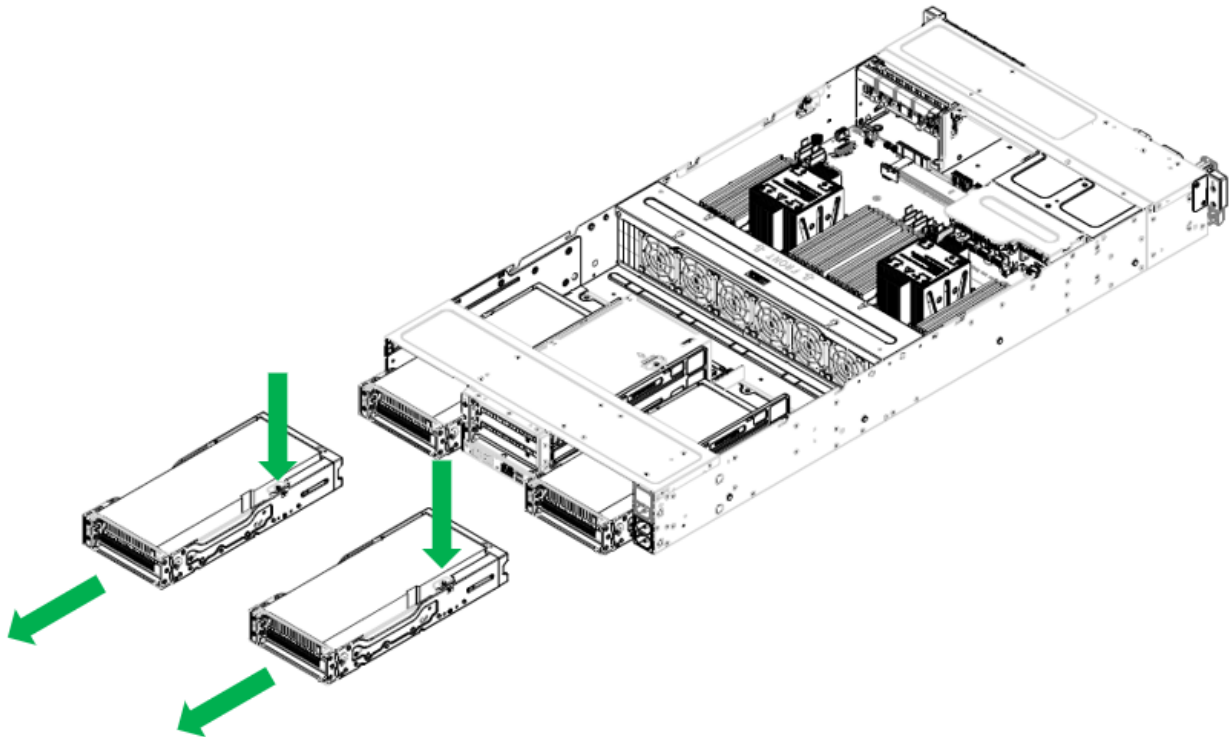
12. Rear Riser Assembly (1U Height GPU Bay)

Type and number of fastenings: One (1) latch per bay.

Tools required: None.

Procedure:

1. Unplug the data and power cables of the components attached to the assembly.
2. Press the release button, then slide the bay outward from the chassis.



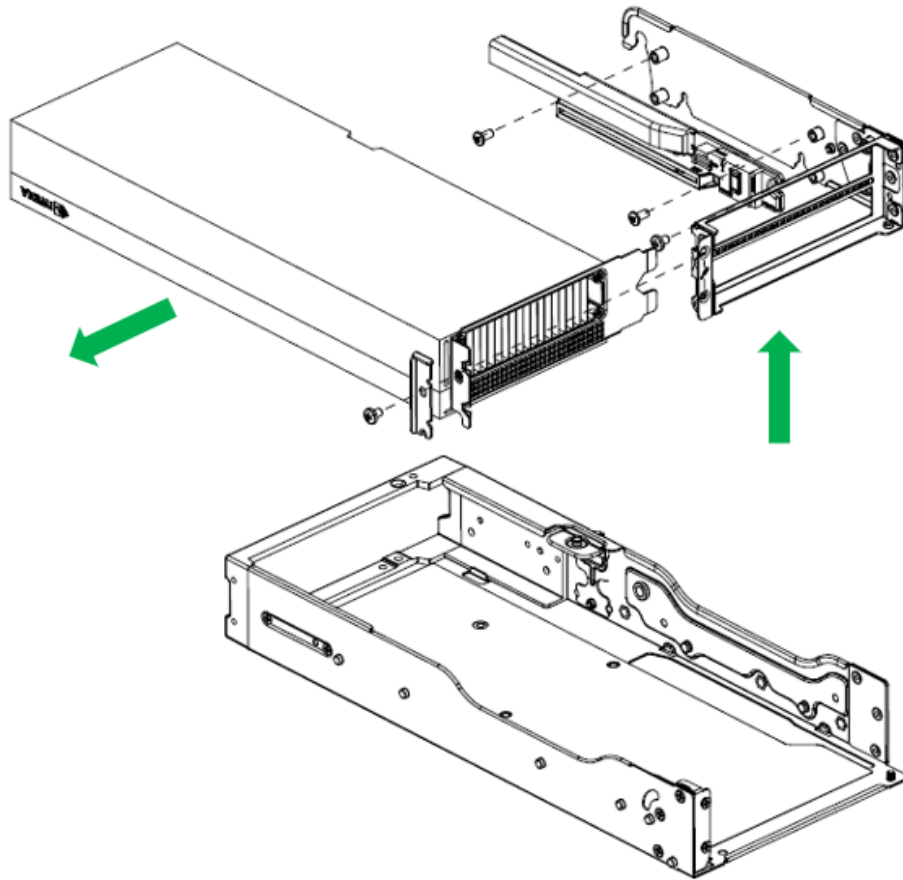
13. GPU (1U Height GPU bay)

Type and number of fastenings: Nine (9) screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the screws and slide the riser card metal subassembly from the rest of the GPU bay.
2. Unscrew the GPU PCIe brackets and unplug the GPUs carefully.



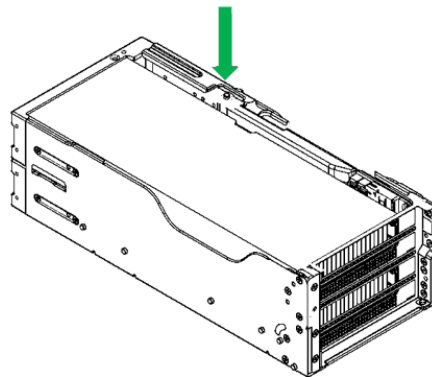
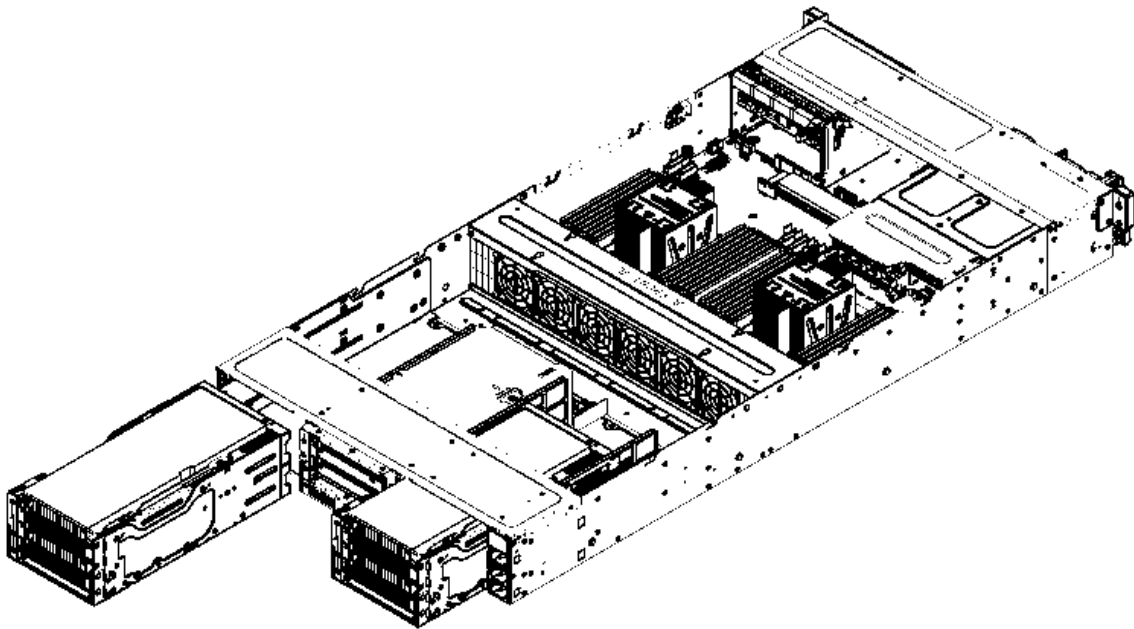
14. Rear Riser Assembly (2U Height GPU Bay)

Type and number of fastenings: One (1) latch per bay.

Tools required: None.

Procedure:

1. Unplug the data and power cables of the components attached to the assembly.
2. Press the release button, then slide the bay outward from the chassis.



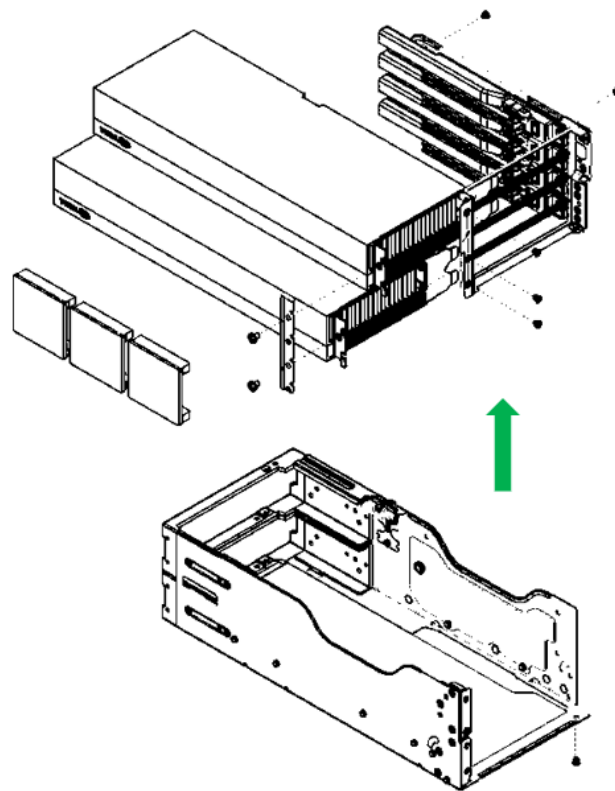
15. GPUs and GPU bridges (2U Height GPU Bay)

Type and number of fastenings: 17 screws

Tools required: Screwdriver with PH1 / PH2 bit.

Procedure:

1. Remove the screws and slide the riser card metal subassembly from the rest of the GPU bay.
2. Carefully unplug the GPU bridges (if installed) and slide away from the GPUs.
3. Unscrew the GPU PCIe brackets and unplug the GPUs carefully and slide away.



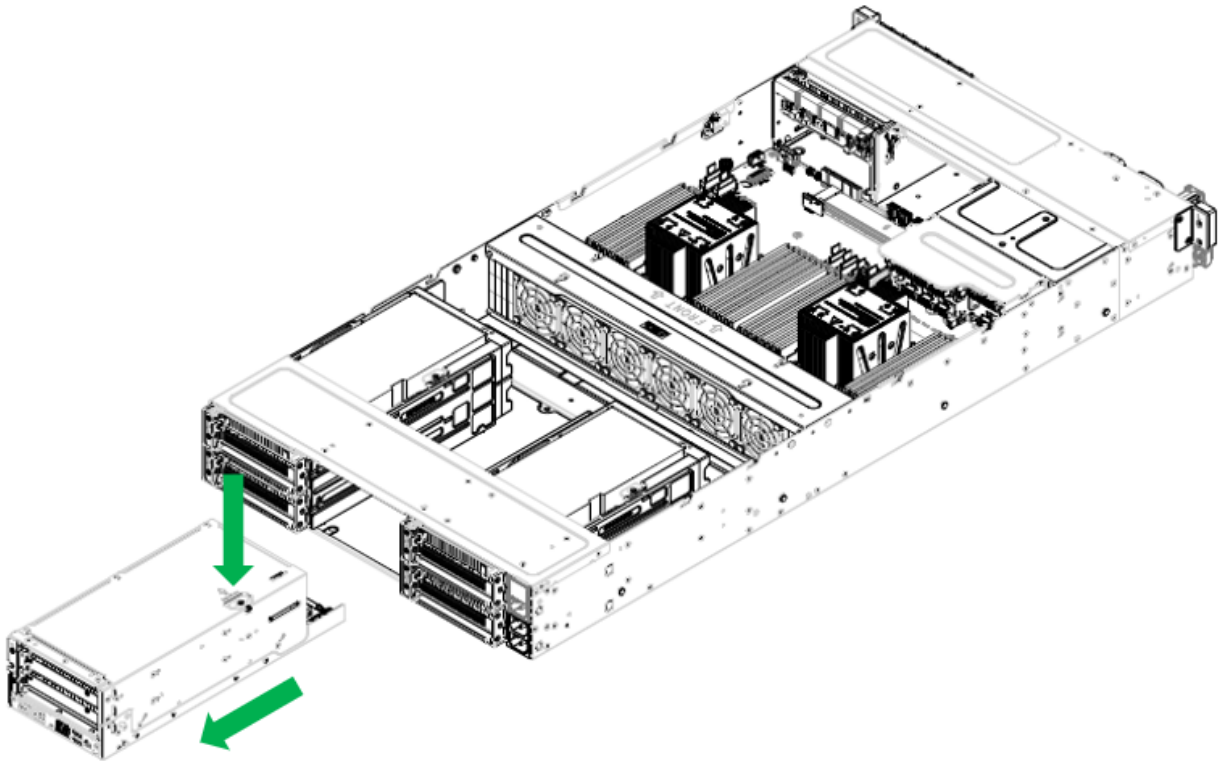
16. Rear Riser Assembly (2U Height IO Bay)

Type and number of fastenings: One (1) latch

Tools required: None.

Procedure:

1. Unplug the data and power cables of the components attached to the assembly.
2. Press the release button, then slide the bay outward from the chassis.



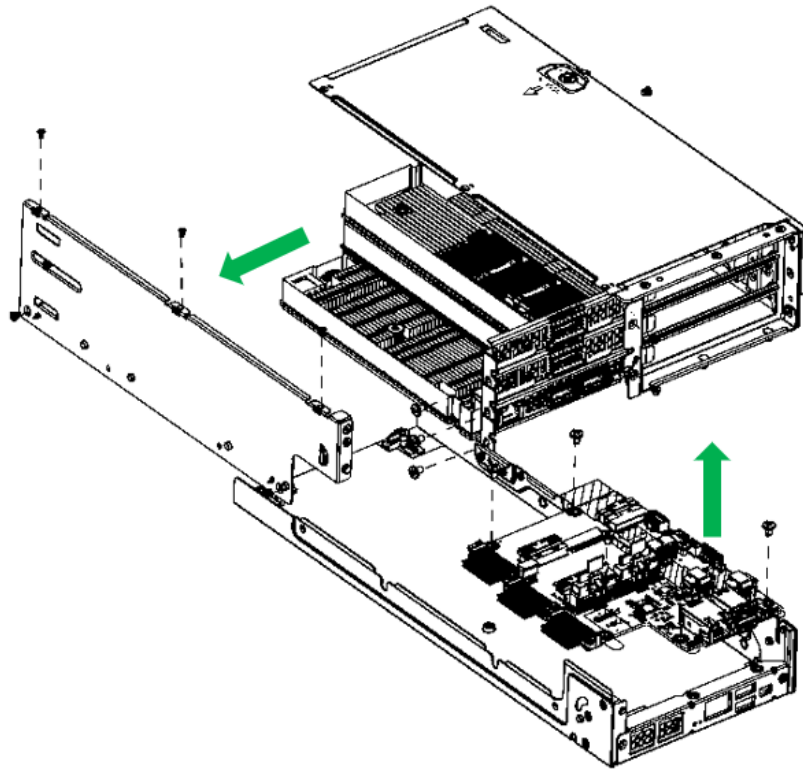
17. Add-On Cards and IO board (2U Height IO Bay)

Type and number of fastenings: 28 screws

Tools required: Screwdriver with PH1 / PH2 bit.

Procedure:

1. Remove the screws and slide the riser card metal subassembly from the rest of the IO bay.
2. Unscrew the add-on-card PCIe brackets and unplug the cards carefully and slide away.
3. Remove the screws and lift the IO board from the bottom of the IO bay.



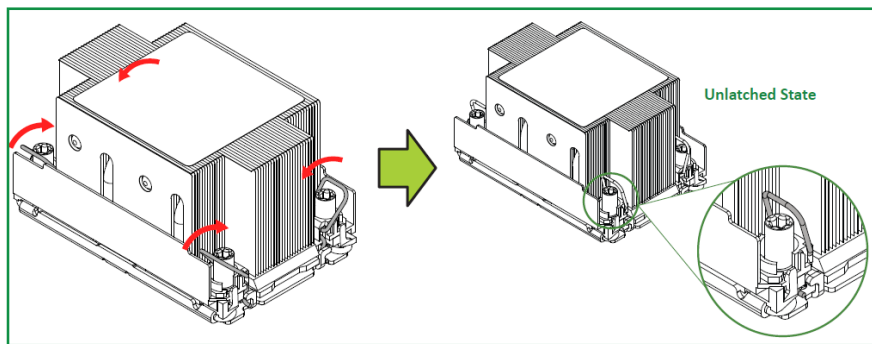
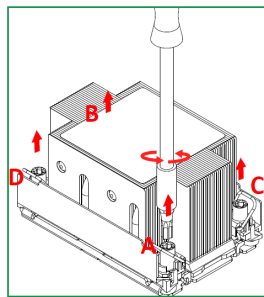
18.Processor and Heatsink

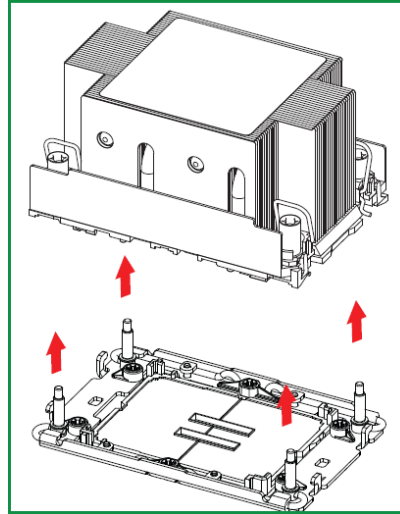
Type and number of fastenings: Four (4) T30 Torx screws.

Tools required: Screwdriver with T30 Torx bit.

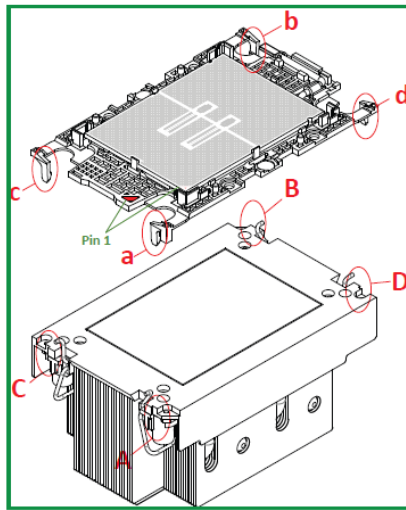
Procedure:

1. Loosen the four peek nuts on the heatsink in the sequence of A, B, C, then #D.
2. Once the peek nuts are loosened from the processor socket, press the rotating wires inward to unlatch the processor heatsink module from the socket.
3. Gently lift the processor heatsink module upward to remove it from the processor socket.

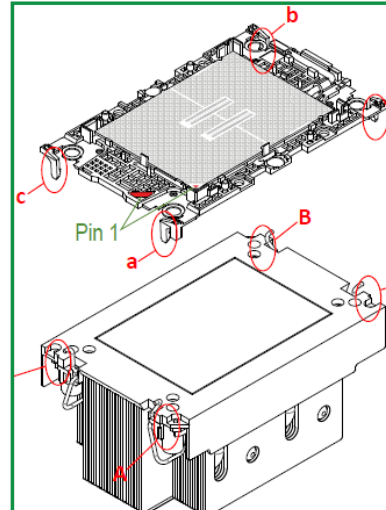




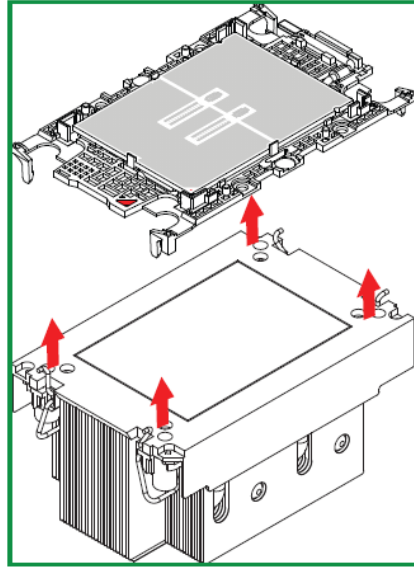
4. Detach the four plastic clips (marked a, b, c, and d below) on the processor carrier assembly from the four corners of the heatsink (marked A, B, C, and D).
5. When all plastic clips are detached from the heatsink, remove the processor carrier assembly from the heatsink.



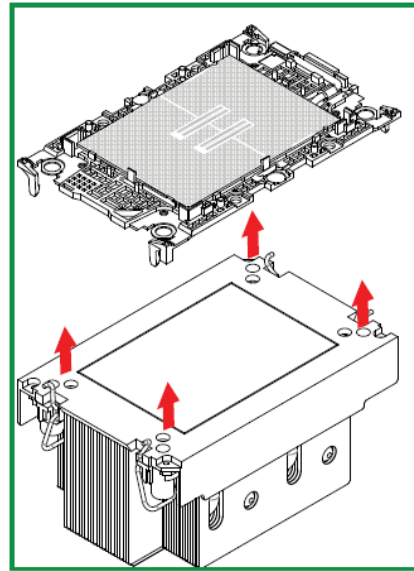
SP XCC



SP MCC

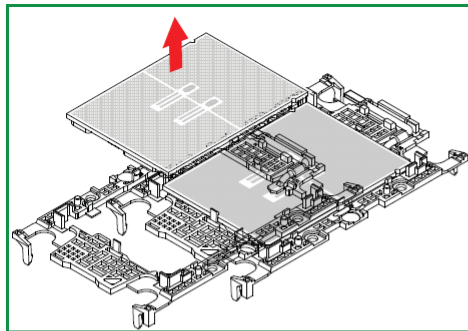


SP XCC

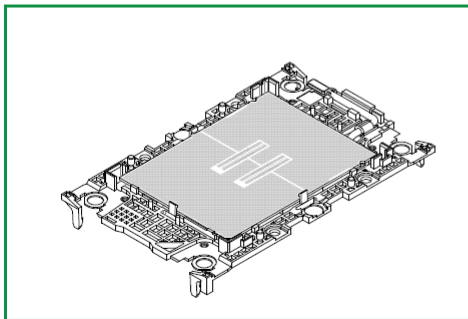
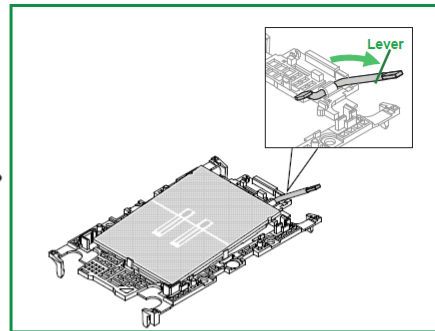


SP MCC

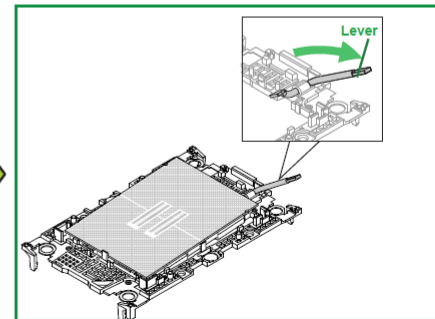
6. Unlock the lever from its locking position and push the lever upward to disengage the processor from the processor carrier.
 7. Once the processor is loosened from the carrier, carefully remove the processor from the processor carrier.
- Note: To avoid damaging the processor and its pins, please handle the processor with care.*

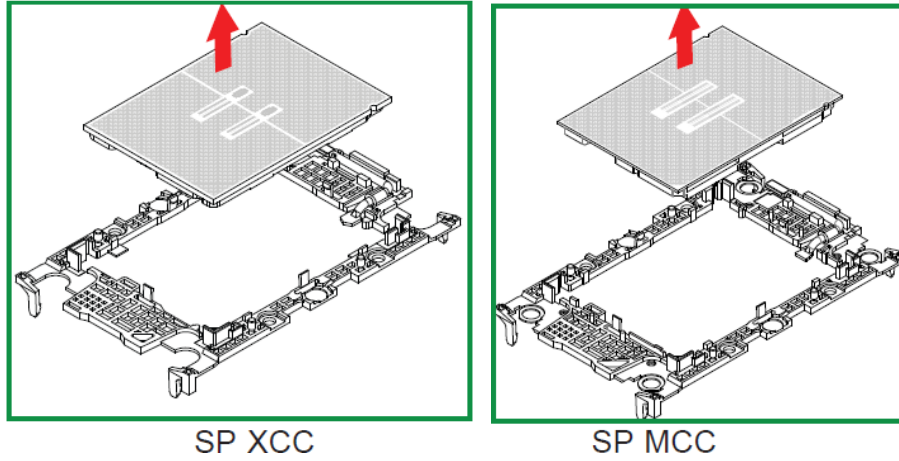


CPU Carrier Assembly (carrier E1A)



CPU Carrier Assembly (carrier E1B)





19. Motherboard

Type and number of fastenings: Eight (8) screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Remove the screws and lift the motherboard from its base.

